



Materials Declaration

Package	TQFP
Body Size	10 X 10
LeadCount	44
Option	Pb Free

Molding Compound			
Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	1.02 E-02	35923
SiO2 Filler	86	1.10 E-01	386175
Phenol Resin	5	6.39 E-03	22452
Antimony_Sb2O3	0.4	5.11 E-04	1796
Brominated Resin	0.4	5.11 E-04	1796
Carbon Black	0.2	2.56 E-04	898

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	1.04 E-01	365573
Ni	3	3.24 E-03	11400
Si	0.65	7.03 E-04	2470
Mg	0.15	1.62 E-04	570

Internal Leadframe Plating			
	% of Plating	Weight (g)	PPM
Ag	100	1.70 E-03	5974

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	100	3.40 E-03	11949

Bond Wires			
	% of Wire	Weight (g)	PPM
Au	99.99	8.58 E-04	3016

Chip			
	% of Chip	Weight (g)	PPM
Si	100	3.77 E-02	132556

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Resin	26	1.29 E-03	4537
Ag Filler	74	3.67 E-03	12914

Package Totals	
Weight (g)	PPM
2.85 E-01	1000000

Molding Compound		
Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Die Attach Paste		
Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

STS-SU-B

6/7/04





Materials Declaration

Package	TQFP
Body Size	10 X 10
LeadCount	44
Option	Sn/Pb

Molding Compound			
Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	1.02 E-02	35923
SiO2 Filler	86	1.10 E-01	386175
Phenol Resin	5	6.39 E-03	22452
Antimony_Sb2O3	0.4	5.11 E-04	1796
Brominated Resin	0.4	5.11 E-04	1796
Carbon Black	0.2	2.56 E-04	898

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	1.04 E-01	365573
Ni	3	3.24 E-03	11400
Si	0.65	7.03 E-04	2470
Mg	0.15	1.62 E-04	570

Internal Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Ag	100	1.70 E-03	5974

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	85	2.89 E-03	1.02 E+04
Pb	15	5.10 E-04	1.79 E+03

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	8.58 E-04	3016

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100	3.77 E-02	132556

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Resin	26	1.29 E-03	4537
Ag Filler	74	3.67 E-03	12914

Molding Compound		
Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Die Attach Paste		
Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

Package Totals	
Weight (g)	PPM
2.85 E-01	1000000

STS-SU-A

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